

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Gurer

Serial No:

Filed: June 4, 2001

For: PLASMA DEPOSITION OF SPIN CHUCKS
TO REDUCE CONTAMINATION OF
SILICON WAFERS

) Group No.:

) Examiner:

Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Before examination, please consider the following amendments and remarks.

In the Claims:

Please cancel claims 1-44.

Please add the following new claims 45-64:

1 45. (New) An apparatus for delivering media to a wafer, comprising:
2 a housing defining a process chamber;
3 a media delivery member coupled to the process chamber;
4 a spin chuck positioned in the process chamber, the spin chuck having a wafer
5 support surface, wherein the wafer support surface is covered with a coating layer,
6 the coating layer being in a solid state and substantially free of voids; and
7 a vacuum supply line coupled to the spin chuck.

1 46. (New) The apparatus of claim 45, wherein the coating layer is a
2 dielectric coating layer.

1 47. (New) The apparatus of claim 45, wherein the coating layer has a
2 composition including a substance from the chemical family SiO_xCH_y , with x